

ABSTRACT

A heat sink member capable of suppressing development of cracks and chaps in manufacturing, suppressing

5 enlargement of a thermal expansion coefficient and suppressing lowering of thermal conductivity is obtained.

This heat sink member comprises a ply member (1) mainly composed of Cu, a substrate (2) mainly composed of Mo and a brazing layer (4) consisting of an Sn-Cu alloy (Sn: 1

10 mass % to 13 mass %) arranged between the ply member and the substrate for bonding the ply member and the substrate to each other.